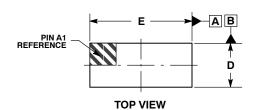
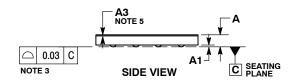


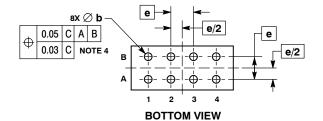
WLCSP8, 0.97x2.25X0.265

CASE 567TE **ISSUE A**

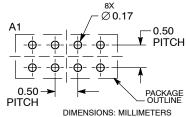
DATE 10 MAR 2017







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DIMENSION 6 IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C. DIMENSION A3 IS AN OPTIONAL BACKSIDE
- COATING LAYER.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.24	0.265	0.29	
A1	0.04 REF			
А3	0.025 REF			
b	0.12	0.17	0.22	
D	0.92	0.97	1.02	
Е	2.20	2.25	2.30	
е	0.50 BSC			

GENERIC MARKING DIAGRAM*



= Assembly Location

WL = Wafer Lot

Υ = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

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